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1. Scope

This specification applied to the products of current sensing resistor of metal plate for Lead-Free RLFC series manufactured by TA-I TECHNOLOGY CO.,LTD.

2. Type Designation

RLFC Item	25 Series No.	<u>F</u> Resistance tolerance	<u>E</u> Packaging	<u>C</u> Power rating	<u>M</u> Metal	R001 Resistance
F: 4 –wire asymmetric	25:2512	F:±1% G:±2% J:±5%	E: Embossed Tape	C=1W	M=Mn/Cu	e.g: $R001=1mΩ$ $R002=2mΩ$

3. Features

Series	RLFC25
Size	2512
Power(W)	1W
Resistance Value(mΩ)	$1 \text{m}\Omega \le R \le 10 \text{m}\Omega$
Operation Temperature Range	-55°C~+170°C
TCR (ppm/°C)	±50ppm/°C
Tolerance	±1%, ±2%, ±5%
Insulation Resistance	Over 100MΩ
Maximum Working Voltage(V)	(P*R)1/2

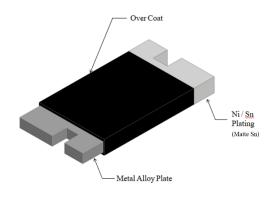
*Note: The specifications and characteristics of this product are not suitable for series and parallel use.



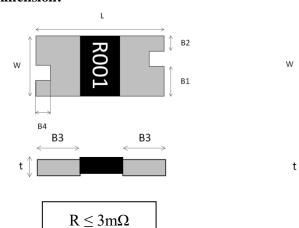
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4. Construction and Dimension

4.1 Construction:



4.2 Dimension:



	Dimension	L	W	t	B1
	SPEC (mm)	6.4±0.2	3.2±0.2	0.7±0.2	1.6±0.2
RLFC25	Dimension	B2	В3		B4
	SDEC (mm)	0.0+0.2	2.2±0.2 (R	0.7.00	
	SPEC (mm)	0.9 ± 0.2	1.0+0.2 (R	0.7±0.2	

Unit: mm

L

 $R>3m\Omega$

В3

В3



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5. Reliability Tests:

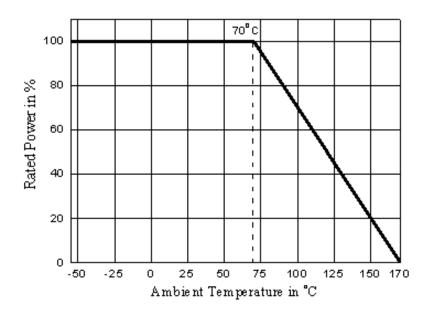
Test Items	Reference	Condition of Test	Test Limits
Temperature Coefficient of Resistance	IEC60115-1 4.8	+25 ~ 125°C	Refer 4.0
High Temperature Exposure (Storage)	AEC-Q200-REV E-Test 3 MIL-STD202 Method 108	T=170°C,1000hrs, Measurement at 24hrs after test conclusion.	<±(1%+0.0005Ω)
Temperature Cycling	AEC-Q200-REV E-Test 4 JESD22 Method JA-104	1000Cycle (-55°C to 155°C), Measurement at 24hrs after test conclusion.	<±(0.5%+0.0005Ω)
Short time overload	IEC60115-1 4.13	5 X rated power for 5s.	<±(0.5%+0.0005Ω)
Biased Humidity	AEC-Q200-REV E-Test 7 MIL-STD-202 Method 103	10% Rated power at 85°C, RH:85%,1000Hrs, Measurement at 24hrs after test conclusion.	<±(1%+0.0005Ω)
Operation life	AEC-Q200-REV E-Test 8 MIL-STD-202 Method 108	1000 hours TA=70°C at 100% rated power. 90min ON and 30 min OFF. Measurement at 24±4 hours after test conclusion.	<±(1%+0.0005Ω)
External Visual	AEC-Q200-REV E-Test 9 MIL-STD-883 Method 2009	Electrical test not required. Inspect device construction, marking and workmanship.	
Physical Dimension	AEC-Q200-REV E-Test 10 JESD22 Method JB-100	Verify physical dimensions to the applicable device detail specification. Note: User(s) and Suppliers spec. Electrical test not required.	
Resistance to Solvents	a: Isopropyl Alcohol: Mineral Sp = 1:3 b: Terpene Defluxer		Marking and protective layer cannot be detached
Resistance to Soldering Heat	AEC-Q200-REV E-Test 15 MIL-STD-202 Method 210	T=260+/-5°C solder,10+/-1 sec dwell.	<±(0.5%+0.0005Ω)
Mechanical Shock	AEC-Q200-REV E-Test 13 MIL-STD-202 Method 213	100g's, Normal duration is 6ms, half sine shock pulse.	<±(0.5%+0.0005Ω)
Resistance to vibration	AEC-Q200-REV E-Test 14 MIL-STD-202 Method 204	5g's for 20min.12cycles, 10-2000Hz.	<±(0.5%+0.0005Ω)
Board Flex	AEC-Q200-REV E-Test 21 AEC-Q200-005	Min 2mm deflection ,60sec.	<±(0.5%+0.0005Ω)
Flammability	AEC-Q200-REV E-Test 20 UL-94	V-0 or V-1 are acceptable, Electrical test not required.	V-0
ESD	AEC-Q200-REV E-Test 17 AEC-Q200-002 or ISO/DIS 10605	verify the voltage setting at 500V.	<±(1%+0.0005Ω)
Solderability	AEC-Q200-REV E-Test 18 J-STD-002	aging 4 hours at 155 °C dry heat Lead-free solder bath at 235±3 °C Dipping time: 3±0.5 seconds.	> 95% area covered with tin



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Terminal Strength (SMD)	AEC-Q200-REV E-Test 22 AEC-Q200-006	Force of 1.8kg for 60 seconds. Remarks: 0201-NA	<±(1%+0.0005Ω)
Low Temperature Storage	IEC60115-1 4.23.4 JIS C 5201-1 4.23.4	-55°C, 1000hrs	<±(1%+0.0005Ω)

5.1 Derating Curve:



5.2 Rated Current:

The rated current is calculated by the following Formula:

 $I = \sqrt{P \div R}$

I: Rated Current(A)

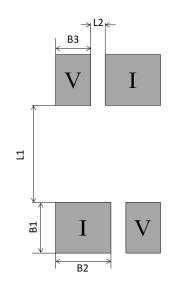
P: Rated Power(W)

R: Resistance Value(Ω)



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6. Recommended Solder Pad Dimension



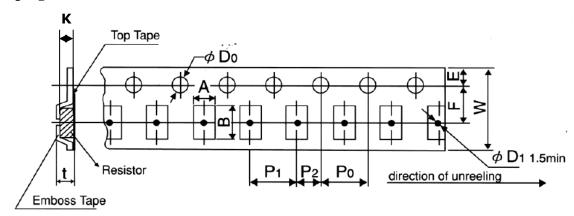
Resistance Range(mΩ)	L1	L2	B1	B2	В3
$R \le 3m\Omega$	1.3±0.1	0.6±0.1	3.1±0.1	2.1±0.1	1.3±0.1
$R > 3m\Omega$	4.1±0.1	0.6±0.1	2.1±0.1	2.1±0.1	1.3±0.1

Unit: mm

7. Number of Package

4000 Pieces / package

8. Taping



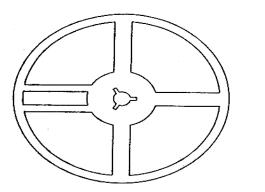
Packing	Type	A	В	W	F	Е	P_1	P_2	P_0	$\phi\mathrm{D}_0$	t	\mathbf{K}_0
Emboss Tape	RLFC25	3.6 ±0.2	6.9 ±0.2	12 ±0.2	5.5 ±0.05	1.75 ±0.1	4.0 ±0.1	2.0 ±0.05	4.0 ±0.05	<i>ψ</i> 1.5 (+0.1/-0)	1.2 ±0.15	1.0 ±0.15

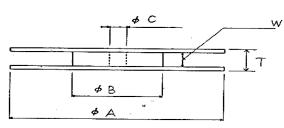
Unit: mm



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9. Reel Specification:



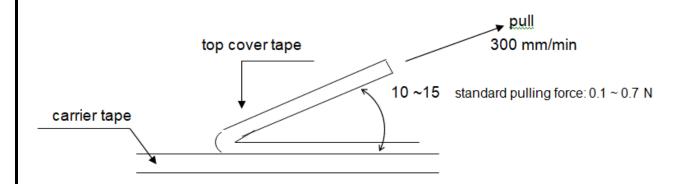


Series	φА	φВ	φС	W	T
RLFC25	180 -3	60 ±1.0	13.0±1.0	13.0±1.0	15.4±2.0

Unit: mm

10. Peeling Strength of Top Cover Tape:

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.





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11.	Storage	Conditions:
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Temperature: 5°C~35°C, Humidity: 40%~75%

MSL level 1

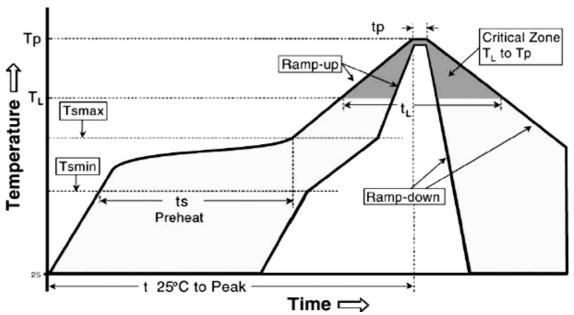
12. Shelf Life:

2 years from manufacturing date.



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13. Recommend IR – Reflow profile: (solder: Sn96.5 / Ag3 / Cu0.5)



Alloyed Re-flow times: 3 times

Remark: To avoid discoloration phenomena of chip on terminal electrodes,

please use N2 Re-flow furnace.

Iron Solder:350±10°C, 3+1/-0 sec, 1 time

Profile Feature	Lead (Pb)-Free Assembly	
Average ramp-up rate (Tsmax to Tp)	3°C / second max.	
Preheat		
- Temperature Min (Ts _{min})	150°C	
- Temperature Max (Ts _{max})	200°C	
- Time (Ts _{min} to Ts _{max}) (ts)	60 -120 seconds	
Time maintained above :		
- Temperature (T _L)	217°C	
- Time (T _L)	60-150 seconds	
Peak Temperature (Tp)	260°C	
Time within $^{+0}_{-5}$ °C of actual Peak	10 accords	
Temperature $(tp)^2$	10 seconds	
Ramp-down Rate	6°C/second max.	
Time 25°C to Peak Temperature	8mimutes max.	



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14. ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in approval sheet.

15. Manufacturing Country & City:

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